



**FOR IMMEDIATE RELEASE**

**EV GROUP BOOSTS HIGH-VOLUME MANUFACTURING PERFORMANCE ACROSS PRODUCT LINES WITH NEW XT FRAME EQUIPMENT PLATFORM**

***New Flexible, Modular Equipment Architecture Increases Tool Functionality and Boosts Throughput Capabilities***

**ST. FLORIAN, Austria, December 5, 2011** — [EV Group \(EVG\)](#), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced it has introduced a new equipment platform, dubbed the XT Frame, that extends process throughput and tool functionality for virtually all of its current volume-manufacturing product offerings. Specifically designed to address new requirements from its high-volume manufacturing (HVM) customers, the XT Frame can accommodate up to nine process modules—doubling EVG's previous maximum processing capability for significantly increased throughput. In addition, customers have greater flexibility in combining different process modules on a single tool platform. Products built on the new XT Frame platform are available immediately.

An increasing number of device types, including components for high-volume consumer products such as smart phones and handsets, are being produced at the wafer level—driving the need for new solutions to increase production throughput in the fab. EVG's new XT Frame platform provides an equipment front-end module with an ultra-fast handling system, enough module spaces for the parallel processing of several wafers, as well as up to four FOUP (front opening unified pod) load ports. This, combined with a material buffer in the form of a local FOUP storage system (LFSS), enables highly efficient continuous mode operation. Moreover, the new design addresses additional customer requirements such as high process flexibility through the combination of different types of process modules on the same piece of equipment, easy upgradeability, further improved serviceability and a small overall footprint in the fab.

"The XT Frame equipment platform is a significant step forward for EV Group's product offerings for high-volume manufacturing environments," stated Paul Lindner, executive technology director for EV Group. "We are committed to developing innovative solutions that push the performance envelope in order to solve our customers' most pressing technology challenges while lowering their manufacturing costs. We see an immediate need for greater volume manufacturing capability in the advanced packaging and 3D interconnect space, which is why we've chosen our [EVG®850TB/DB](#) system as the first tool to be built on the XT Frame platform."

The new XT Frame architecture is an extension of EVG's field-proven standard equipment platform, which provides up to five process modules. The standard equipment platform has also just recently been upgraded to provide enhanced automation capabilities and increased system throughput. As an example, EVG's new flagship model in the [GEMINI FB fusion wafer bonder](#) family, launched at SEMICON Taiwan 2011, is now also available with an optional equipment front end module, a faster handling system and a local material buffer.

EVG's XT Frame platform supports solutions across all of the company's addressable markets, but is especially beneficial for advanced packaging/3D interconnect applications with TSVs (through-silicon vias). In this area, the new platform can, for example, further enhance the performance of EVG's benchmark temporary bonding/debonding and thin wafer processing systems. Demo capabilities for the XT Frame are now available on the EVG®850TB/DB, which can also accommodate EVG's new EZR® (Edge Zone Release) and EZD® (Edge Zone Debond) modules to support [ZoneBOND™ technology](#).

- more -



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Those interested in learning more about EVG's new XT Frame equipment platform can visit the company in Chiba City, Japan where EVG will be exhibiting at SEMICON Japan, December 7-9, at booth #6B-606. More information can be found at [www.EVGroup.com](http://www.EVGroup.com)

### **About EV Group**

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple-i approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at [www.EVGroup.com](http://www.EVGroup.com).

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